

BOARD CHARACTERISTICS

Copper Layer Count:2Board Thickness:1.6000 mm

Board overall dimensions:40.8940 mm x 101.4730 mm

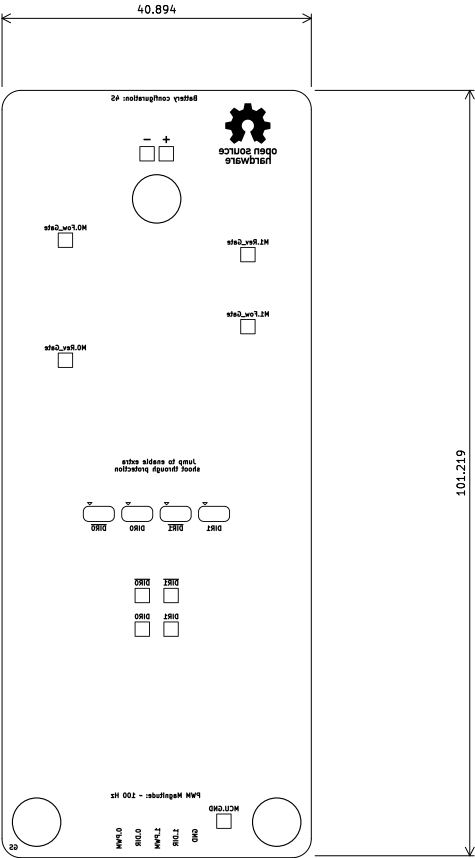
Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.2500 mm

Copper Finish:NoneImpedance Control:No

Castellated pads:NoPlated Board Edge:No

Edge card connectors:No

| Layer Name | Type | Material | Thickness (mm) | Color | Epsilon R | Loss Tangent |
|--------------|---------------------|---------------|----------------|---------------|-----------|--------------|
| F.Silkscreen | Top Silk Screen | Not specified | 0 mm | Not specified | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mm | | 1 | 0 |
| F.Mask | Top Solder Mask | Not specified | 0.01 mm | Not specified | 3.3 | 0 |
| F.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | core | FR4 | 1.51 mm | Not specified | 4.5 | 0.02 |
| B.Cu | copper | | 0.035 mm | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Not specified | 0.01 mm | Not specified | 3.3 | 0 |
| B.Paste | Bottom Solder Paste | | 0 mm | | 1 | 0 |
| B.Silkscreen | Bottom Silk Screen | Not specified | 0 mm | Not specified | 1 | 0 |



George Sleen

Team 5

Sheet:

File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge

Size: A4

Date: 2025-06-19

Rev: A

KiCad E.D.A. 9.0.2

Id: 1/4

BOARD CHARACTERISTICS

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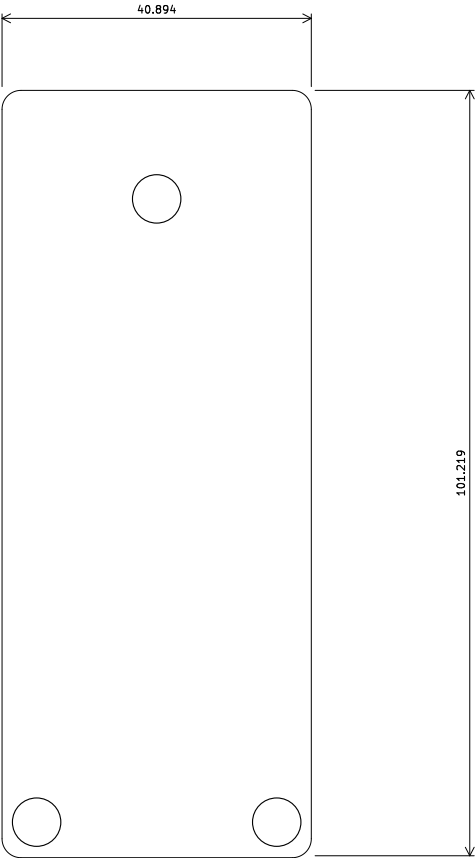
Min track/spacing:0.1000 mm / 0.1000 mmMin hole diameter:0.2500 mm

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Copper Finish:None

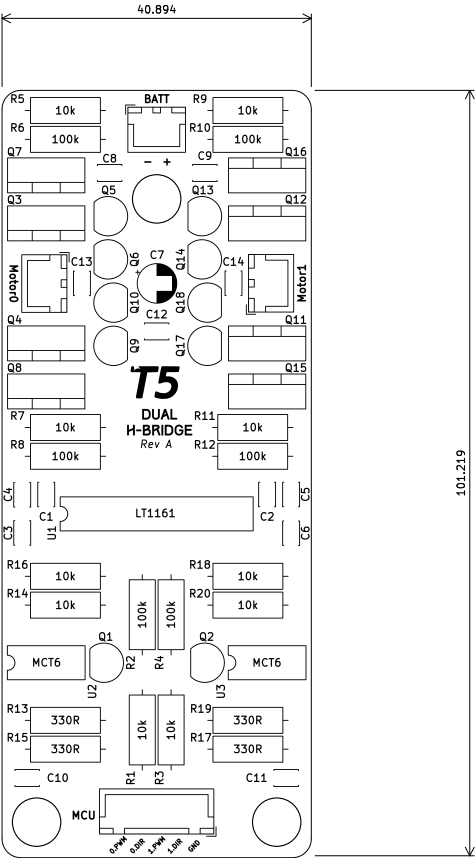
Impedance Control:No

Castellated pads:No

Plated Board Edge:No

Edge card connectors:No

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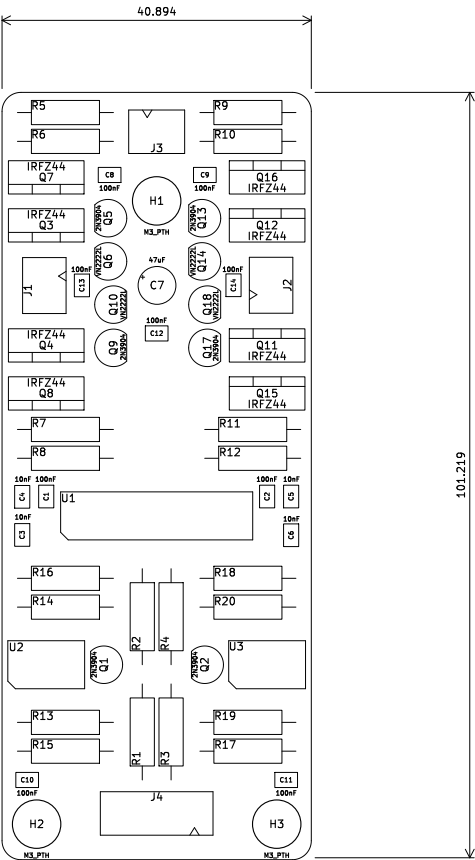
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George Sleen
Team 5

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Title: Dual H-Bridge

Size: A4 Date: 2025-06-19

KiCad E.D.A. 9.0.2

Rev: A

Id: 4/4